Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[TuE1] Innovative Abrasives and Carbon Layer CMP

Session Date	November 11 (Tue.), 2025
Session Time	13:00-14:30
Session Room	Room E (Sicily Room, 1F)

[TuE1-1] **13:00-13:20**

Zirconia as a Novel Abrasive for CMP of Amorphous Carbon Layer (ACL)

Ikjoon Kim, Heesuk Kim, and Jin-Hyung Park (ENF Technology Co., Ltd., Korea)

[TuE1-2] **13:20-13:40**

Development of ITO Stop Ag Slurry Based on Structural Differences in Carboxylic Acids

Junhyuk Kim and Jeongho Lee (Soulbrain Co., Ltd., Korea)

[TuE1-3] [Invited] **13:40-14:10**

Surface Modification Mechanism of Carbon–Metal–Carbon Structures for Enhanced Mechanical Polishing Performance in Hard Amorphous Carbon Layer Chemical-Mechanical-Planarization

Jea-Gun Park, Pil-Su Kim, Min-Uk Jeon, Man-Hyup Han, Hyun-Sung Koh, and Kyoo-Chul Cho (Hanyang Univ., Korea)

[TuE1-4] **14:10-14:30**

Si-Wafer Polishing Rate Enhancing Mechanism Through Accelerating Hydrolysis Reaction at Si-Wafer Surface

Pil-Su Kim, Hye-Min Lee, Min-Uk Jeon, Se-Hui Lee, Su-Bin Kim, Ji-Hye Shin (Hanyang Univ., Korea), Jin-Hyung Park (ENF Technology Co., Ltd., Korea), Kyoo-Chul Cho (Hanyang Univ., Korea), Tae-Dong Kim (Hannam Univ., Korea), Jin-Sub Park, and Jea-Gun Park (Hanyang Univ., Korea)